Material Composition Specification

GPR-4AM Case

Device average mass . . . . . 947 mg

Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.26%	2.48	Si	7440-21-3	0.26%	2.48	2,619
axial lead	wire	79.56%	753.39	Cu	7440-50-8	79.51%	752.94	795,079
				Zn	7440-66-6	0.05%	0.45	475
	moly slug	14.21%	134.6	Mo	7439-98-7	14.21%	134.6	142,133
die attach	solder	0.57%	5.38	Cu	7440-50-8	0.45%	4.3	4,541
				Ag	7440-22-4	0.09%	0.81	855
				P	7723-14-0	0.03%	0.27	285
encapsulation	glass	4.01%	38	Zn	7440-66-6	1.93%	18.24	19,260
				O	7782-44-7	1.47%	13.95	14,730
				B	7440-42-8	0.38%	3.6	3,801
				Si	7440-21-3	0.15%	1.45	1,531
				Pb	7439-92-1	0.08%	0.76	803
plating*	tin/lead process	1.39%	13.17	Sn	7440-31-5	1.18%	11.2	11,827
				Pb	7439-92-1	0.21%	1.97	2,080
	matte tin	1.39%	13.17	Sn	7440-31-5	1.39%	13.17	13,907

*For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.